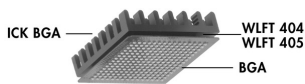


Data sheet Product ICK BGA 27 x 27 x 22



Heatsinks and active heatsinks for processors>Heatsinks for BGAs
27 x 27 x 22 mm, for IC design BGA and others

Features

way of fixation:

- therm. conductive foil
- therm. cond. adhesive

socket:

universal

suitable for processor
type:

universal

width:

27 mm

height:

22 mm

plate thickness:

2.5 mm

length:

27 mm

thermal resistance:

10.5 - 2 K/W

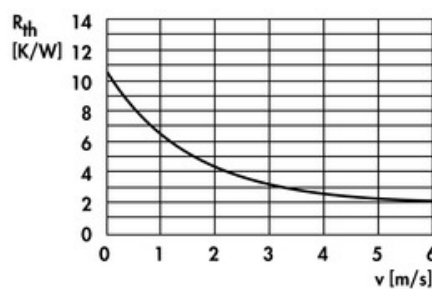
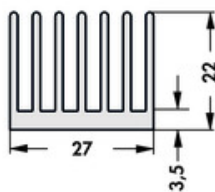
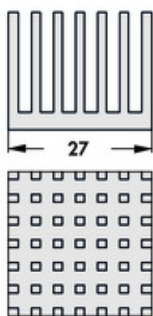
dissipation loss:

9.5 W

surface:

black anodised

Technical Drawing



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